

QDSP-3000 Series

Digital Signage Player

with Intel® Skylake / Kaby Lake S-Series Processors



- Intel® Skylake / Kaby Lake S-Series Processors (LGA1151 Socket)
- Intel® H110 / Q170 Chipset
- 2x DDR4 SO-DIMM
- 2x HDMI2.0, 1x DP for video output
- 1x Line-in, 1x Line-out, 1x Mic-in, 1x S/PDIF for audio
- 2x GbE LAN for Ethernet
- 6x USB3.0 or 4x USB3.0 + 2x USB2.0, 1x COM for peripherals
- 1x 2.5" SATA HDD / SSD, 2x mPCIe/mSATA or 2x mPCIe for storage / expansion
- TPM and iAMT support (Q170 model only)



Product Overview

The QDSP-3000 Series is a BOX PC powered by Intel® Skylake / Kaby Lake S-Series processors with up to Intel® HD Graphics 630 integrated and support for up to 32GB 2x DDR4 SO-DIMM memory. Combined with a variety of video / audio interfaces, including 2x HDMI2.0, 1x DP, 1x Line-in, 1x Line-out, 1x Mic-in and 1x S/PDIF, it is an ideal platform for video and graphics intensive applications, such as digital signage, medical imaging or gaming.

Equipped with 1x 2.5" SATA HDD / SSD, 6x USB, 1x COM, 2x LAN, 2x mPCIe or 2x mPCIe/mSATA, it provides multiple interface options for data storage / backup, peripheral and network connection / expansion to match the varieties of possible applications. In addition, the compact volume allows easy integration into space-constrained applications.

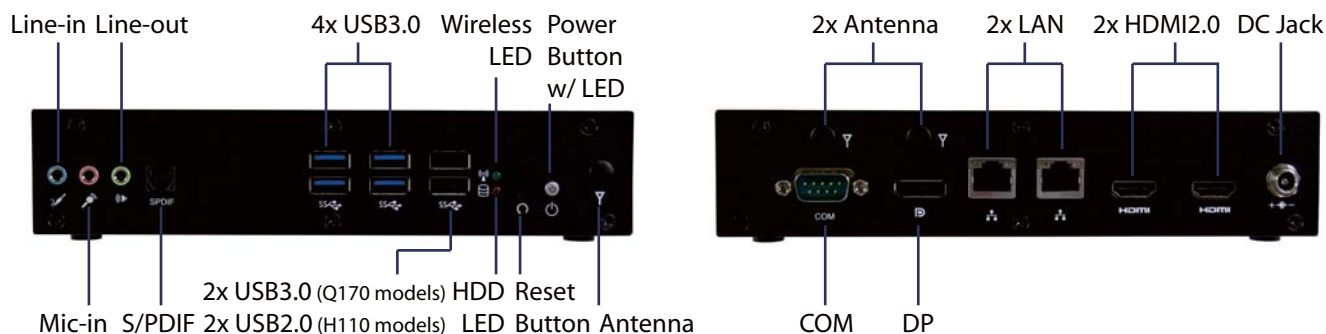
Technical Information

CPU Support
Intel® Skylake S-Series Processors (FCLGA1151 socket, 35W TDP)
Intel® Kaby Lake S-Series Processors (FCLGA1151 socket, 35W TDP)
Chipset
Intel® H110
Intel® Q170
Memory
2x DDR4 1866/2133 SO-DIMM up to 32GB (Skylake models)
2x DDR4 2133/2400 SO-DIMM up to 32GB (Kaby Lake models)
Graphic Controller
Intel® HD Graphics 510 (Skylake Celeron® models)
Intel® HD Graphics 530 (Skylake Core™ models)
Intel® HD Graphics 610 (Kaby Lake Celeron® models)
Intel® HD Graphics 630 (Kaby Lake Core™ models)
Display Interfaces
2x HDMI2.0 (on rear, 4096 x 2160 @ 60Hz)
1x DP (on rear, 4096 x 2304 @ 60Hz)
Multiple Display
Dual Display (H110 models)
Triple Display (Q170 models)
Audio Chipset
Realtek ALC662
Audio Interfaces
1x Line-in (on front)
1x Line-out (on front)
1x Mic-in (on front)
1x S/PDIF (on front)
Ethernet
2x GbE LAN (RJ-45 on rear, Intel® I219-LM, Intel® I210-AT)
USB
4x USB3.0 (Type A on front, H110 models)
6x USB3.0 (Type A on front, Q170 models)
2x USB2.0 (Type A on front, H110 models)
Serial Ports
1x RS-232/422/485 (DB9 on rear)
Storage & Expansion
1x 2.5" SATA HDD / SSD
2x mSATA/mPCIe (1x full size, 1x half size, Q170 models)
2x mPCIe (1x full size, 1x half size, H110 models)
1x SIM Card Cage

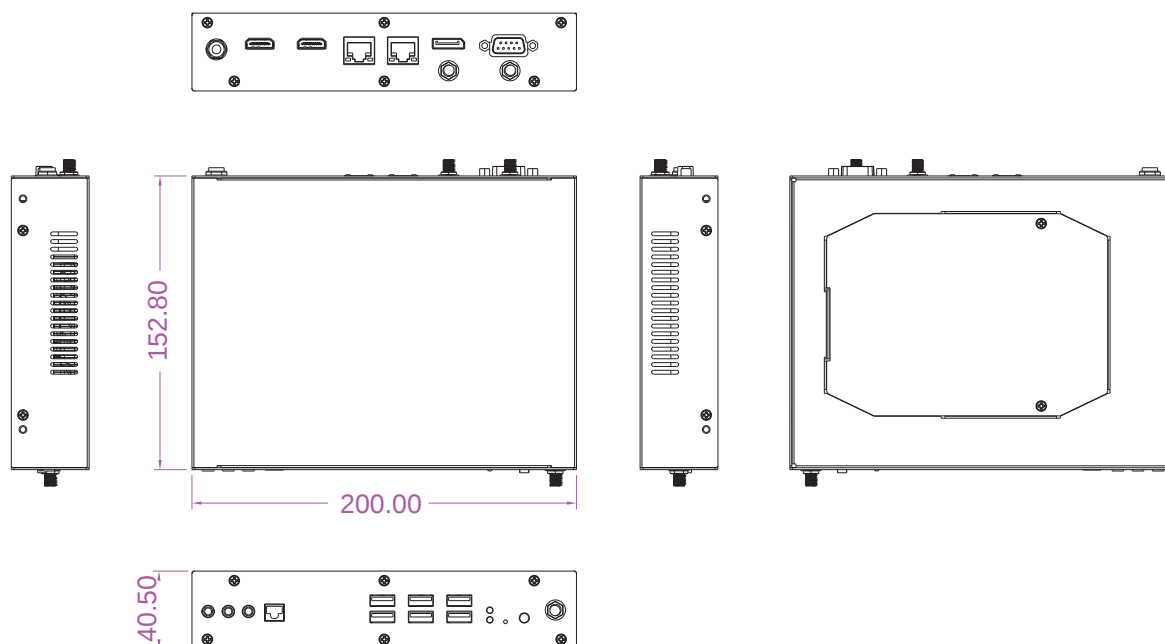
Power Supply
Connector: Lockable DC Jack (on rear)
Input Voltage: DC 19V
Power Adapter: AC to DC, 100V ~ 240V
Firmware
BIOS: AMI uEFI BIOS w/ 128Mb SPI Flash
Watchdog: Programmable WDT to generate system reset event
H/W Monitor: Input & Core Voltages, CPU & System Temperatures
Real Time Clock: Chipset integrated RTC
TPM: TPM support for Q170 models
Infineon SLB 9660 TPM 1.2 for Skylake models
Infineon SLB 9665 TPM 2.0 for Kaby Lake models
iAMT: Supported for Q170 models
System Control & Monitoring
1x Power Button w/ LED (on front)
1x Reset Button (on front)
1x HDD LED (on front)
1x Wireless LED (on front)
Cooling
1x CPU Smart Fan
OS Support
Windows 7 (Skylake only), Windows 8 (Skylake only), Windows 10, Linux
Construction
Metal Chassis
Dimensions (W x D x H)
200 x 152.8 x 40.5 mm / 7.87" x 6.02" x 1.59"
Weight
1000 g / 2.20 lb
Environmental Characteristics
Operation Temp.: 0°C ~ 50°C / 32°F ~ 122°F (Skylake models)
0°C ~ 40°C / 32°F ~ 104°F (Kaby Lake models)
Storage Temp.: -20°C ~ 80°C / -4°F ~ 176°F
Humidity: 0% ~ 90%
Mounting
VESA Mount
Certification
CE, FCC Class A

* HDMI2.0 function is not applicable to the following monitors: LG 27MU67-B, LG 27UD68, AOC U2879VF, LG 65UF850T, QD980, Dell S2817Q & ASUS MX27UQ.

Front & Rear I/O Panels



Mechanical Dimensions



Ordering Information

Article	Description
QDSP-3000	Intel® Skylake-S CPUs, Intel® H110 Chipset, 2x DDR4 SO-DIMM, 2x HDMI2.0, 1x DP, 2x GbE, 4x USB3.0, 2x USB2.0, 1x RS-232/422/485, 2x mPCIe, w/o TPM, w/o iAMT, Op. Temp.: 0°C ~ 50°C
QDSP-3001	Intel® Skylake-S CPUs, Intel® Q170 Chipset, 2x DDR4 SO-DIMM, 2x HDMI2.0, 1x DP, 2x GbE, 6x USB3.0, 1x RS-232/422/485, 2x mPCIe/mSATA, w/ TPM, w/ iAMT, Op. Temp.: 0°C ~ 50°C
QDSP-3010	Intel® Kaby Lake-S CPUs, Intel® H110 Chipset, 2x DDR4 SO-DIMM, 2x HDMI2.0, 1x DP, 2x GbE, 4x USB3.0, 2x USB2.0, 1x RS-232/422/485, 2x mPCIe, w/o TPM, w/o iAMT, Op. Temp.: 0°C ~ 40°C
QDSP-3011	Intel® Kaby Lake-S CPUs, Intel® Q170 Chipset, 2x DDR4 SO-DIMM, 2x HDMI2.0, 1x DP, 2x GbE, 6x USB3.0, 1x RS-232/422/485, 2x mPCIe/mSATA, w/ TPM, w/ iAMT, Op. Temp.: 0°C ~ 40°C

 Optional Accessories

Product Name	Description
VESA Mounting Kit	Hole pattern: 100 mm x 100 mm & 75 mm x 75 mm